Output Capacitor

The output capacitor is selected based on the DC output voltage rating, output ripple voltage specification and ripple current rating.

The selected output capacitor must have a higher rated voltage specification than the maximum desired output voltage including ripple. De-rating needs to be considered for long term reliability.

Output ripple voltage specification is another important factor for selecting the output capacitor. In a buck converter circuit, output ripple voltage is determined by inductor value, switching frequency, output capacitor value and ESR. It can be calculated by the equation below:

$$\Delta V_O = \Delta I_L \times \left(ESR_{CO} + \frac{1}{8 \times f \times C_O} \right)$$

where,

C_O is output capacitor value and

ESR_{CO} is the Equivalent Series Resistor of output capacitor.

When a low ESR ceramic capacitor is used as output capacitor, the impedance of the capacitor at the switching frequency dominates. Output ripple is mainly caused by capacitor value and inductor ripple current. The output ripple voltage calculation can be simplified to:

$$\Delta V_O = \Delta I_L \times \frac{1}{8 \times f \times C_O}$$

If the impedance of ESR at switching frequency dominates, the output ripple voltage is mainly decided by capacitor ESR and inductor ripple current. The output ripple voltage calculation can be further simplified to:

$$\Delta V_O = \Delta I_L \times ESR_{CO}$$

For lower output ripple voltage across the entire operating temperature range, X5R or X7R dielectric type of ceramic, or other low ESR tantalum are recommended to be used as output capacitors.

In a buck converter, output capacitor current is continuous. The RMS current of output capacitor is decided by the peak to peak inductor ripple current. It can be calculated by:

$$I_{CO\_RMS} = \frac{\Delta I_L}{\sqrt{12}}$$

Usually, the ripple current rating of the output capacitor is a smaller issue because of the low current stress. When the buck inductor is selected to be very small and inductor ripple current is high, the output capacitor could be overstressed.

Thermal Management and Layout Consideration

In the AOZ1269-02 buck regulator circuit, high pulsing current flows through two circuit loops. The first loop starts from the input capacitors, to the VIN pin, to the LX pins, to the filter inductor, to the output capacitor and load, and then returns to the input capacitor through ground. Current flows in the first loop when the high side switch is on. The second loop starts from the inductor, to the output capacitors and load, to the low side switch. Current flows in the second loop when the low side switch is on.

In PCB layout, minimizing the two loops area reduces the noise of this circuit and improves efficiency. A ground plane is strongly recommended to connect the input capacitor, output capacitor and PGND pin of the AOZ1269-02.

In the AOZ1269-02 buck regulator circuit, the major power dissipating components are the AOZ1269-02 and output inductor. The total power dissipation of the converter circuit can be measured by input power minus output power.

$$P_{total\_loss} = V_{IN} \times I_{IN} - V_O \times I_O$$

The power dissipation of inductor can be approximately calculated by output current and DCR of inductor and output current.

$$P_{inductor\_loss} = I_O^2 \times R_{inductor} \times 1.1$$

The actual junction temperature can be calculated with power dissipation in the AOZ1269-02 and thermal impedance from junction to ambient.

$$T_{junction} = (P_{total\_loss} - P_{inductor\_loss}) \times \Theta_{JA}$$

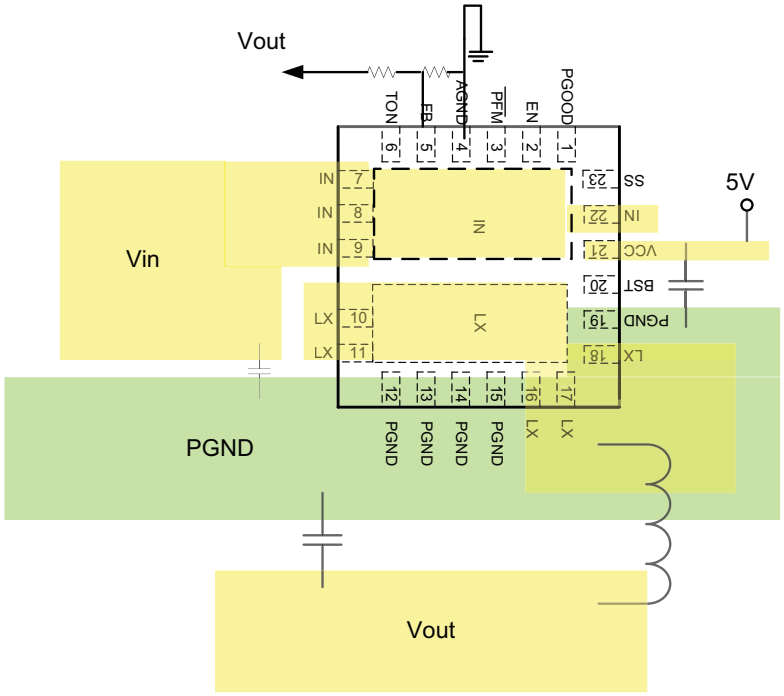
The maximum junction temperature of AOZ1269-02 is 150ºC, which limits the maximum load current capability.

The thermal performance of the AOZ1269-02 is strongly affected by the PCB layout. Extra care should be taken by users during design process to ensure that the IC will operate under the recommended environmental conditions.

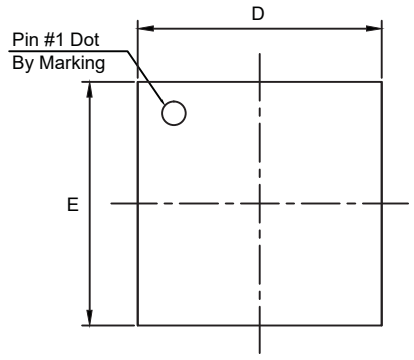
Layout Considerations

Several layout tips are listed below for the best electric and thermal performance.

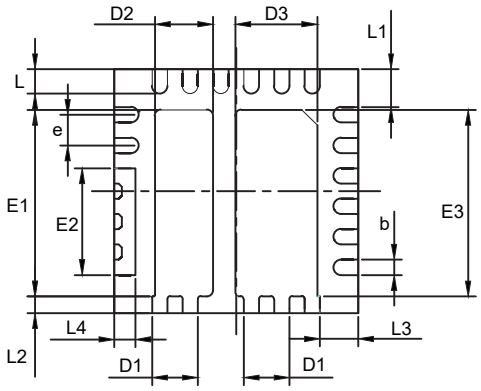
1. The LX pins and pad are connected to internal low side switch drain. They are low resistance thermal conduction path and most noisy switching node. Connect a large copper plane to LX pin to help thermal dissipation.
2. The IN pins and pad are connected to internal high side switch drain. They are also low resistance thermal conduction path. Connect a large copper plane to IN pins to help thermal dissipation.
3. Input capacitors should be connected to the IN pin and the PGND pin as close as possible to reduce the switching spikes.
4. Decoupling capacitor C_{VCC} should be connected to VCC and AGND as close as possible.
5. Voltage divider R1 and R2 should be placed as close as possible to FB and AGND.
6. R_{TON} should be put on PCB reverse side of feedback network or away from FB pin and FB feedback resistors to avoid unwanted touch to short Ton pin and FB together to ground to cause improperly operation.
7. A ground plane is preferred; Pin 19 (PGND) must be connected to the ground plane through via.
8. Keep sensitive signal traces such as feedback trace far away from the LX pins.
9. Pour copper plane on all unused board area and connect it to stable DC nodes, like VIN, GND or VOUT.



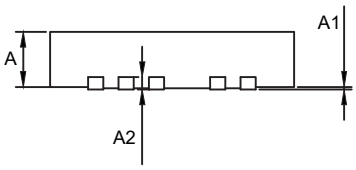
Package Dimensions, QFN 4x4B, 23 Lead EP2_S



TOP VIEW

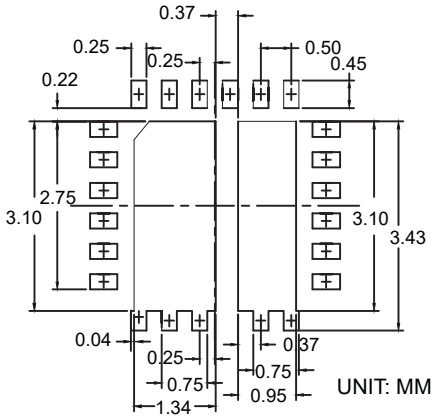


BOTTOM VIEW



SIDE VIEW

RECOMMENDED LAND PATTERN



Dimensions in millimeters

Symbols	Min.	Typ.	Max.
A	0.80	0.90	1.00
A1	0.00	—	0.05
A2		0.2 REF	
E	3.90	4.00	4.10
E1	2.95	3.05	3.15
E2	1.65	1.75	1.85
E3	2.95	3.05	3.15
D	3.90	4.00	4.10
D1	0.65	0.75	0.85
D2	0.85	0.95	1.05
D3	1.24	1.34	1.44
L	0.35	0.40	0.45
L1	0.57	0.62	0.67
L2	0.23	0.28	0.33
L3	0.57	0.62	0.67
L4	0.30	0.35	0.40
b	0.20	0.25	0.30
e		0.50 BSC	

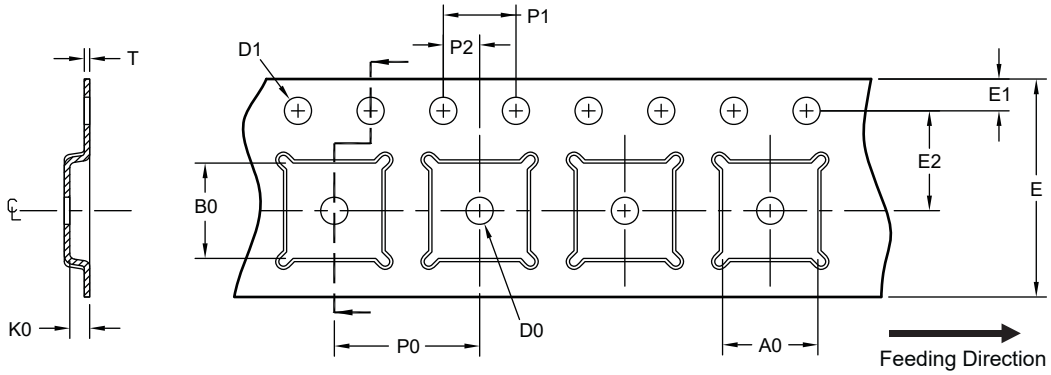
Dimensions in inches

Symbols	Min.	Typ.	Max.
A	0.031	0.035	0.039
A1	0.000	—	0.002
A2		0.008 REF	
E	0.153	0.157	0.161
E1	0.116	0.120	0.124
E2	0.065	0.069	0.073
E3	0.116	0.120	0.124
D	0.153	0.157	0.161
D1	0.026	0.030	0.034
D2	0.033	0.037	0.041
D3	0.049	0.053	0.057
L	0.014	0.016	0.018
L1	0.022	0.024	0.026
L2	0.009	0.011	0.013
L3	0.022	0.024	0.026
L4	0.012	0.014	0.016
b	0.008	0.010	0.012
e		0.020 BSC	

Notes:
1. Controlling dimensions are in millimeters. Converted inch dimensions are not necessarily exact.
2. Tolerance: ± 0.05 unless otherwise specified.
3. Radius on all corners is 0.152 max., unless otherwise specified.
4. Package wrapage: 0.012 max.
5. No plastic flash allowed on the top and bottom lead surface.
6. Pad planarity: ± 0.102
7. Crack between plastic body and lead is not allowed.

Tape and Reel Dimensions, QFN 4x4, 23 Lead EP2_S

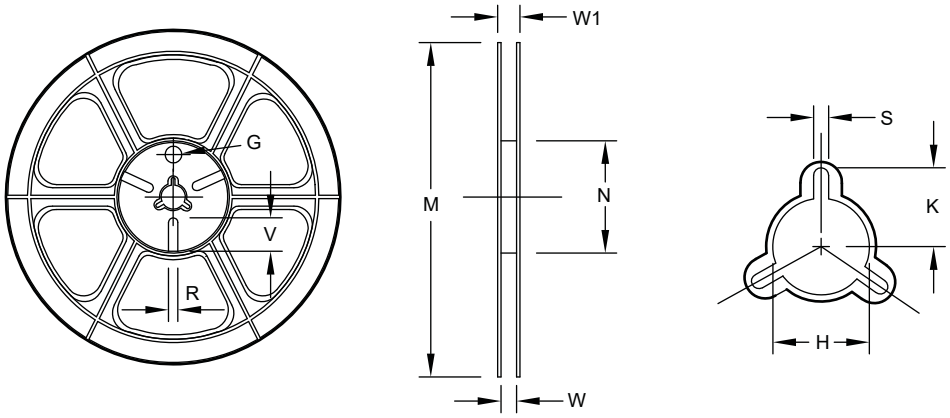
Carrier Tape



UNIT: mm

Package	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
QFN 4x4 (12mm)	4.35 ±0.10	4.35 ±0.10	1.10 ±0.10	1.50 Min.	1.50 +0.10/-0	12.00 ±0.30	1.75 ±0.10	5.50 ±0.05	8.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.30 ±0.05

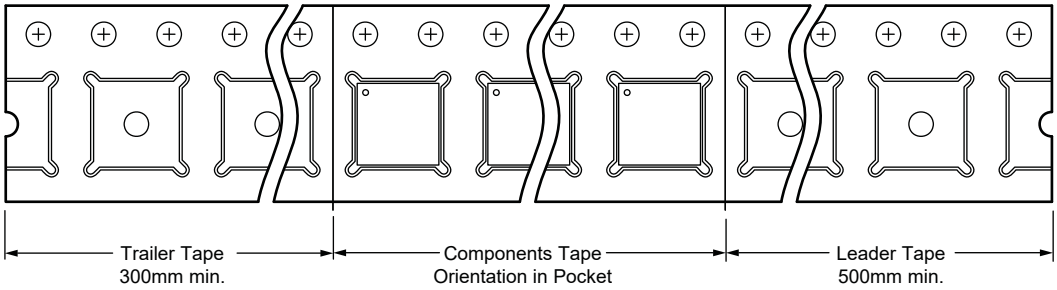
Reel



UNIT: mm

Tape Size	Reel Size	M	N	W	W1	H	K	S	G	R	V
12mm	ø330	ø330.0 ±2.0	ø79.0 ±1.0	12.4 +2.0/-0.0	17.0 +2.6/-1.2	ø13.0 ±0.5	10.5 ±0.2	2.0 ±0.5	—	—	—

Leader/Trailer and Orientation



Part Marking